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## Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

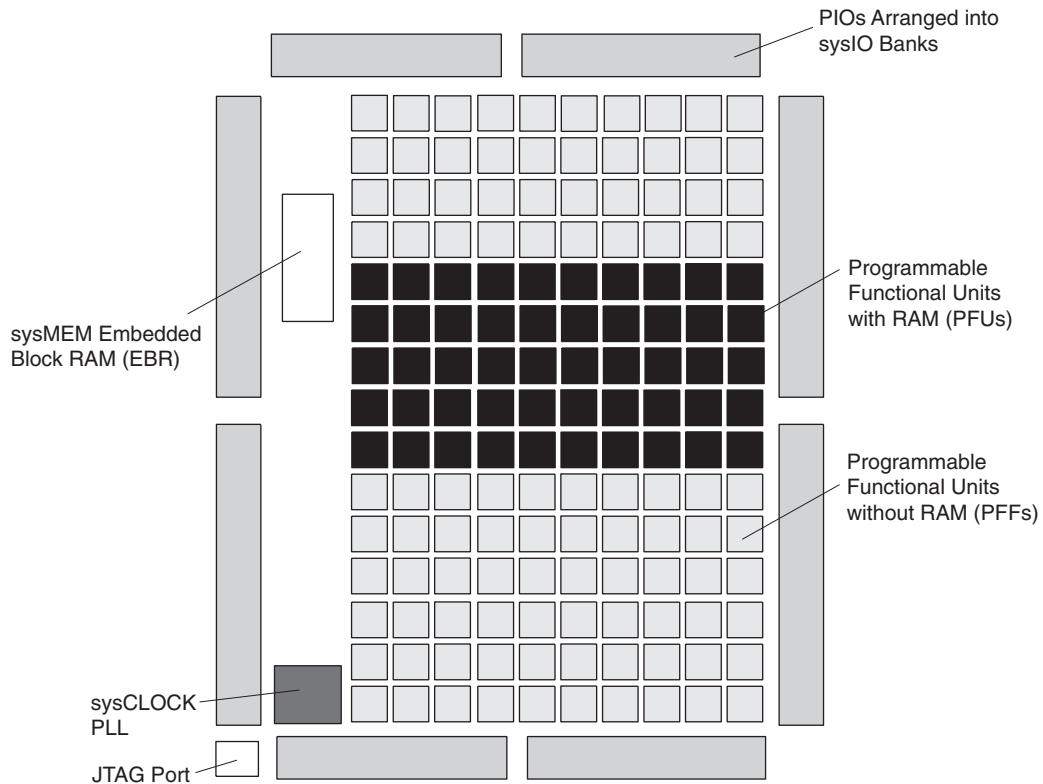
## **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

### **Details**

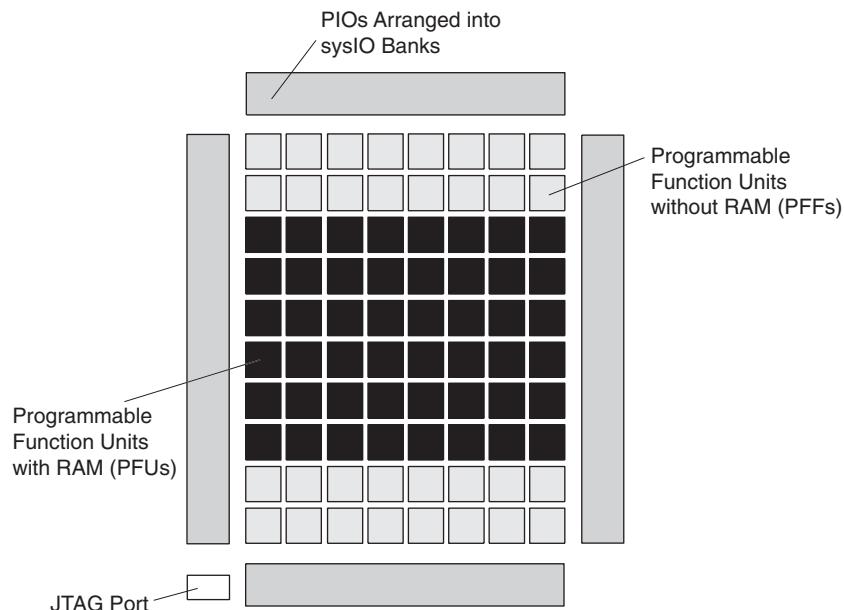
Product Status	Obsolete
Number of LABs/CLBs	285
Number of Logic Elements/Cells	2280
Total RAM Bits	28262
Number of I/O	211
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-LFBGA, CSPBGA
Supplier Device Package	256-CABGA (14x14)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo2280e-5b256c">https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo2280e-5b256c</a>

**Figure 2-1. Top View of the MachXO1200 Device<sup>1</sup>**



1. Top view of the MachXO2280 device is similar but with higher LUT count, two PLLs, and three EBR blocks.

**Figure 2-2. Top View of the MachXO640 Device**



### Modes of Operation

Each Slice is capable of four modes of operation: Logic, Ripple, RAM, and ROM. The Slice in the PFF is capable of all modes except RAM. Table 2-2 lists the modes and the capability of the Slice blocks.

**Table 2-2. Slice Modes**

	Logic	Ripple	RAM	ROM
PFU Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	SP 16x2	ROM 16x1 x 2
PFF Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	N/A	ROM 16x1 x 2

**Logic Mode:** In this mode, the LUTs in each Slice are configured as 4-input combinatorial lookup tables (LUT4). A LUT4 can have 16 possible input combinations. Any logic function with four inputs can be generated by programming this lookup table. Since there are two LUT4s per Slice, a LUT5 can be constructed within one Slice. Larger lookup tables such as LUT6, LUT7, and LUT8 can be constructed by concatenating other Slices.

**Ripple Mode:** Ripple mode allows the efficient implementation of small arithmetic functions. In ripple mode, the following functions can be implemented by each Slice:

- Addition 2-bit
- Subtraction 2-bit
- Add/Subtract 2-bit using dynamic control
- Up counter 2-bit
- Down counter 2-bit
- Ripple mode multiplier building block
- Comparator functions of A and B inputs
  - A greater-than-or-equal-to B
  - A not-equal-to B
  - A less-than-or-equal-to B

Two additional signals, Carry Generate and Carry Propagate, are generated per Slice in this mode, allowing fast arithmetic functions to be constructed by concatenating Slices.

**RAM Mode:** In this mode, distributed RAM can be constructed using each LUT block as a 16x2-bit memory. Through the combination of LUTs and Slices, a variety of different memories can be constructed.

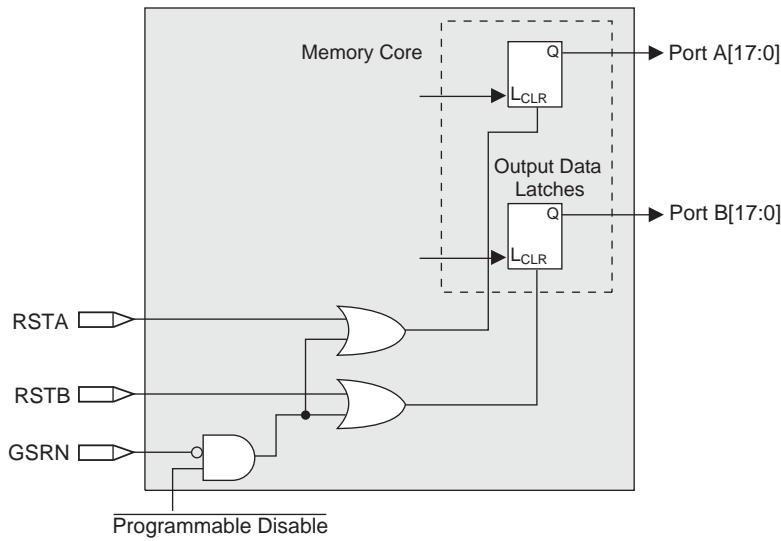
The ispLEVER design tool supports the creation of a variety of different size memories. Where appropriate, the software will construct these using distributed memory primitives that represent the capabilities of the PFU. Table 2-3 shows the number of Slices required to implement different distributed RAM primitives. Figure 2-6 shows the distributed memory primitive block diagrams. Dual port memories involve the pairing of two Slices. One Slice functions as the read-write port, while the other companion Slice supports the read-only port. For more information on RAM mode in MachXO devices, please see details of additional technical documentation at the end of this data sheet.

**Table 2-3. Number of Slices Required For Implementing Distributed RAM**

	SPR16x2	DPR16x2
Number of Slices	1	2

Note: SPR = Single Port RAM, DPR = Dual Port RAM

**Figure 2-13. Memory Core Reset**

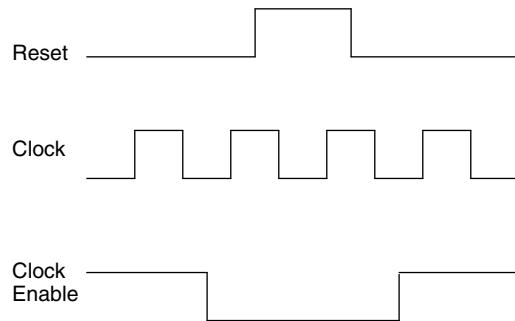


For further information on the sysMEM EBR block, see the details of additional technical documentation at the end of this data sheet.

#### EGR Asynchronous Reset

EGR asynchronous reset or GSR (if used) can only be applied if all clock enables are low for a clock cycle before the reset is applied and released a clock cycle after the reset is released, as shown in Figure 2-14. The GSR input to the EGR is always asynchronous.

**Figure 2-14. EGR Asynchronous Reset (Including GSR) Timing Diagram**



If all clock enables remain enabled, the EGR asynchronous reset or GSR may only be applied and released after the EGR read and write clock inputs are in a steady state condition for a minimum of  $1/f_{MAX}$  (EGR clock). The reset release must adhere to the EGR synchronous reset setup time before the next active read or write clock edge.

If an EGR is pre-loaded during configuration, the GSR input must be disabled or the release of the GSR during device Wake Up must occur before the release of the device I/Os becoming active.

These instructions apply to all EGR RAM, ROM and FIFO implementations. For the EGR FIFO mode, the GSR signal is always enabled and the WE and RE signals act like the clock enable signals in Figure 2-14. The reset timing rules apply to the RPReset input vs the RE input and the RST input vs. the WE and RE inputs. Both RST and RPReset are always asynchronous EGR inputs.

Note that there are no reset restrictions if the EGR synchronous reset is used and the EGR GSR input is disabled

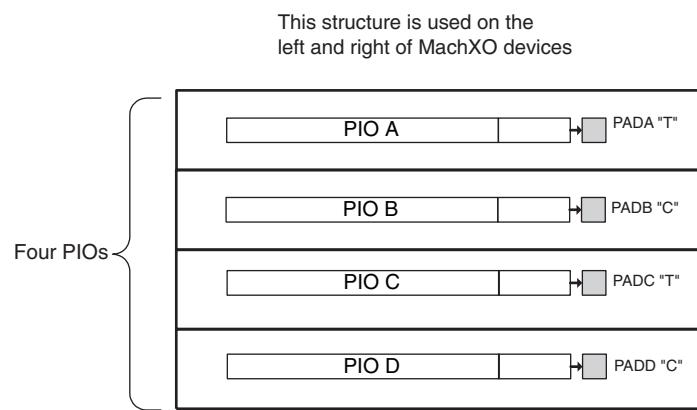
## PIO Groups

On the MachXO devices, PIO cells are assembled into two different types of PIO groups, those with four PIO cells and those with six PIO cells. PIO groups with four IOs are placed on the left and right sides of the device while PIO groups with six IOs are placed on the top and bottom. The individual PIO cells are connected to their respective sysIO buffers and PADs.

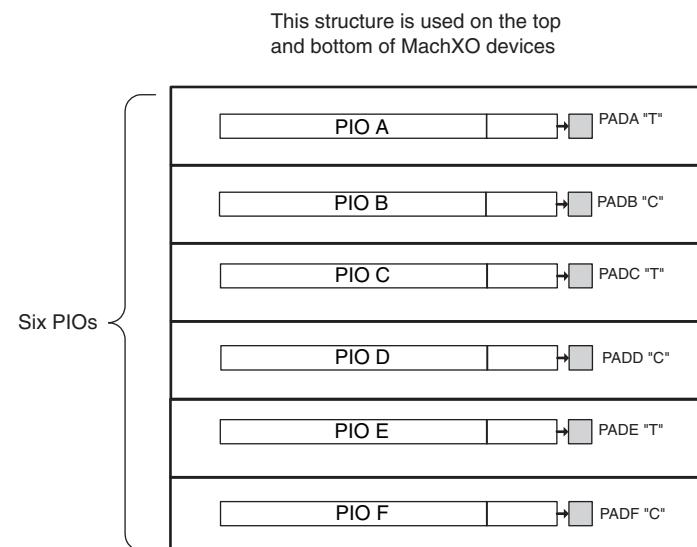
On all MachXO devices, two adjacent PIOs can be joined to provide a complementary Output driver pair. The I/O pin pairs are labeled as "T" and "C" to distinguish between the true and complement pins.

The MachXO1200 and MachXO2280 devices contain enhanced I/O capability. All PIO pairs on these larger devices can implement differential receivers. In addition, half of the PIO pairs on the left and right sides of these devices can be configured as LVDS transmit/receive pairs. PIOs on the top of these larger devices also provide PCI support.

**Figure 2-15. Group of Four Programmable I/O Cells**



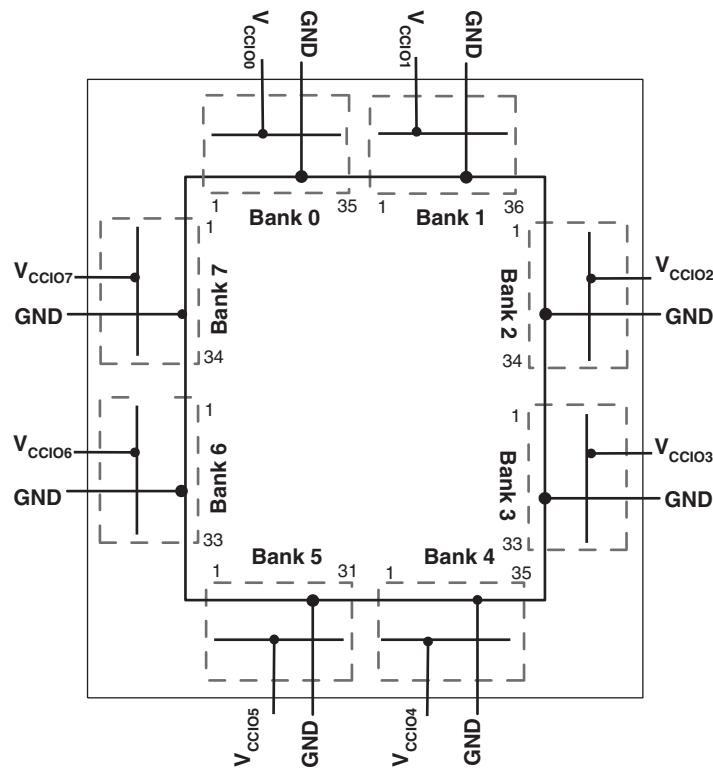
**Figure 2-16. Group of Six Programmable I/O Cells**



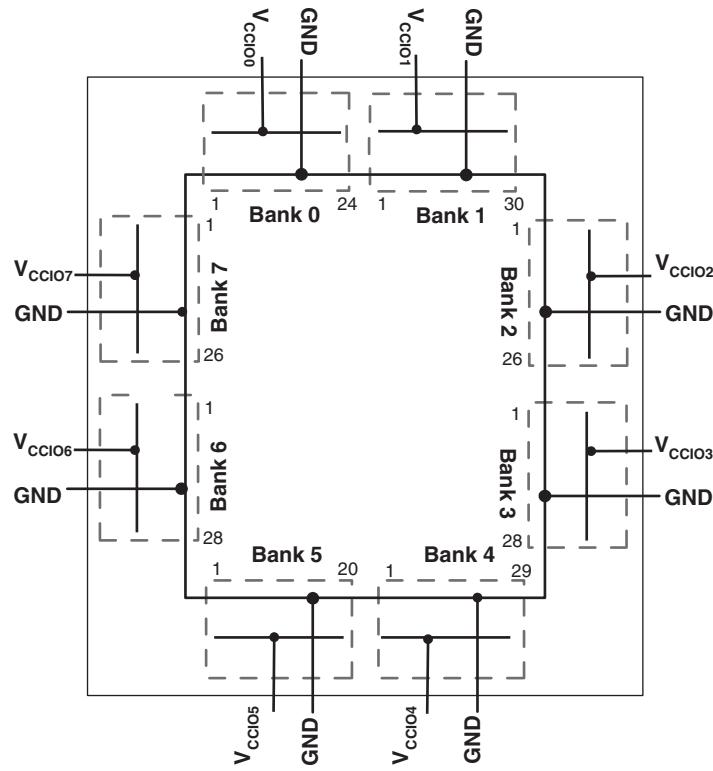
## PIO

The PIO blocks provide the interface between the sysIO buffers and the internal PFU array blocks. These blocks receive output data from the PFU array and a fast output data signal from adjacent PFUs. The output data and fast

**Figure 2-18. MachXO2280 Banks**



**Figure 2-19. MachXO1200 Banks**



the system. These capabilities make the MachXO ideal for many multiple power supply and hot-swap applications.

## Sleep Mode

The MachXO "C" devices ( $V_{CC} = 1.8/2.5/3.3V$ ) have a sleep mode that allows standby current to be reduced dramatically during periods of system inactivity. Entry and exit to Sleep mode is controlled by the SLEEPN pin.

During Sleep mode, the logic is non-operational, registers and EBR contents are not maintained, and I/Os are tri-stated. Do not enter Sleep mode during device programming or configuration operation. In Sleep mode, power supplies are in their normal operating range, eliminating the need for external switching of power supplies. Table 2-11 compares the characteristics of Normal, Off and Sleep modes.

**Table 2-11. Characteristics of Normal, Off and Sleep Modes**

Characteristic	Normal	Off	Sleep
SLEEPN Pin	High	—	Low
Static $I_{CC}$	Typical <10mA	0	Typical <100uA
I/O Leakage	<10 $\mu$ A	<1mA	<10 $\mu$ A
Power Supplies VCC/VCCIO/VCCAUX	Normal Range	0	Normal Range
Logic Operation	User Defined	Non Operational	Non operational
I/O Operation	User Defined	Tri-state	Tri-state
JTAG and Programming circuitry	Operational	Non-operational	Non-operational
EBR Contents and Registers	Maintained	Non-maintained	Non-maintained

## SLEEPN Pin Characteristics

The SLEEPN pin behaves as an LVCMOS input with the voltage standard appropriate to the VCC supply for the device. This pin also has a weak pull-up, along with a Schmidt trigger and glitch filter to prevent false triggering. An external pull-up to VCC is recommended when Sleep Mode is not used to ensure the device stays in normal operation mode. Typically, the device enters sleep mode several hundred nanoseconds after SLEEPN is held at a valid low and restarts normal operation as specified in the Sleep Mode Timing table. The AC and DC specifications portion of this data sheet shows a detailed timing diagram.

## Oscillator

Every MachXO device has an internal CMOS oscillator. The oscillator can be routed as an input clock to the clock tree or to general routing resources. The oscillator frequency can be divided by internal logic. There is a dedicated programming bit to enable/disable the oscillator. The oscillator frequency ranges from 18MHz to 26MHz.

## Configuration and Testing

The following section describes the configuration and testing features of the MachXO family of devices.

### IEEE 1149.1-Compliant Boundary Scan Testability

All MachXO devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant test access port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port shares its power supply with one of the VCCIO Banks (MachXO256:  $V_{CCIO1}$ ; MachXO640:  $V_{CCIO2}$ ; MachXO1200 and MachXO2280:  $V_{CCIO5}$ ) and can operate with LVCMOS3.3, 2.5, 1.8, 1.5, and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.

## Device Configuration

All MachXO devices contain a test access port that can be used for device configuration and programming.

The non-volatile memory in the MachXO can be configured in two different modes:

- In IEEE 1532 mode via the IEEE 1149.1 port. In this mode, the device is off-line and I/Os are controlled by BSCAN registers.
- In background mode via the IEEE 1149.1 port. This allows the device to remain operational in user mode while reprogramming takes place.

The SRAM configuration memory can be configured in three different ways:

- At power-up via the on-chip non-volatile memory.
- After a refresh command is issued via the IEEE 1149.1 port.
- In IEEE 1532 mode via the IEEE 1149.1 port.

Figure 2-22 provides a pictorial representation of the different programming modes available in the MachXO devices. On power-up, the SRAM is ready to be configured with IEEE 1149.1 serial TAP port using IEEE 1532 protocols.

### Leave Alone I/O

When using IEEE 1532 mode for non-volatile memory programming, SRAM configuration, or issuing a refresh command, users may specify I/Os as high, low, tristated or held at current value. This provides excellent flexibility for implementing systems where reconfiguration or reprogramming occurs on-the-fly.

### **TransFR (Transparent Field Reconfiguration)**

TransFR (TFR) is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a single ispVM command. See TN1087, [Minimizing System Interruption During Configuration Using TransFR Technology](#) for details.

### Security

The MachXO devices contain security bits that, when set, prevent the readback of the SRAM configuration and non-volatile memory spaces. Once set, the only way to clear the security bits is to erase the memory space.

For more information on device configuration, please see details of additional technical documentation at the end of this data sheet.

## Typical Building Block Function Performance<sup>1</sup>

### Pin-to-Pin Performance (LVCMS25 12mA Drive)

Function	-5 Timing	Units
<b>Basic Functions</b>		
16-bit decoder	6.7	ns
4:1 MUX	4.5	ns
16:1 MUX	5.1	ns

### Register-to-Register Performance

Function	-5 Timing	Units
<b>Basic Functions</b>		
16:1 MUX	487	MHz
16-bit adder	292	MHz
16-bit counter	388	MHz
64-bit counter	200	MHz
<b>Embedded Memory Functions (1200 and 2280 Devices Only)</b>		
256x36 Single Port RAM	284	MHz
512x18 True-Dual Port RAM	284	MHz
<b>Distributed Memory Functions</b>		
16x2 Single Port RAM	434	MHz
64x2 Single Port RAM	320	MHz
128x4 Single Port RAM	261	MHz
32x2 Pseudo-Dual Port RAM	314	MHz
64x4 Pseudo-Dual Port RAM	271	MHz

1. The above timing numbers are generated using the ispLEVER design tool. Exact performance may vary with device and tool version. The tool uses internal parameters that have been characterized but are not tested on every device.

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### Derating Logic Timing

Logic Timing provided in the following sections of the data sheet and the ispLEVER design tools are worst case numbers in the operating range. Actual delays may be much faster. The ispLEVER design tool from Lattice can provide logic timing numbers at a particular temperature and voltage.

## MachXO Internal Timing Parameters<sup>1</sup>

Over Recommended Operating Conditions

Parameter	Description	-5		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
<b>PFU/PFF Logic Mode Timing</b>								
t <sub>LUT4_PFU</sub>	LUT4 delay (A to D inputs to F output)	—	0.28	—	0.34	—	0.39	ns
t <sub>LUT6_PFU</sub>	LUT6 delay (A to D inputs to OFX output)	—	0.44	—	0.53	—	0.62	ns
t <sub>LSR_PFU</sub>	Set/Reset to output of PFU	—	0.90	—	1.08	—	1.26	ns
t <sub>SUM_PFU</sub>	Clock to Mux (M0,M1) input setup time	0.10	—	0.13	—	0.15	—	ns
t <sub>HM_PFU</sub>	Clock to Mux (M0,M1) input hold time	-0.05	—	-0.06	—	-0.07	—	ns
t <sub>SUD_PFU</sub>	Clock to D input setup time	0.13	—	0.16	—	0.18	—	ns
t <sub>HD_PFU</sub>	Clock to D input hold time	-0.03	—	-0.03	—	-0.04	—	ns
t <sub>CK2Q_PFU</sub>	Clock to Q delay, D-type register configuration	—	0.40	—	0.48	—	0.56	ns
t <sub>LE2Q_PFU</sub>	Clock to Q delay latch configuration	—	0.53	—	0.64	—	0.74	ns
t <sub>LD2Q_PFU</sub>	D to Q throughput delay when latch is enabled	—	0.55	—	0.66	—	0.77	ns
<b>PFU Dual Port Memory Mode Timing</b>								
t <sub>CORAM_PFU</sub>	Clock to Output	—	0.40	—	0.48	—	0.56	ns
t <sub>SUDATA_PFU</sub>	Data Setup Time	-0.18	—	-0.22	—	-0.25	—	ns
t <sub>HDATA_PFU</sub>	Data Hold Time	0.28	—	0.34	—	0.39	—	ns
t <sub>SUADDR_PFU</sub>	Address Setup Time	-0.46	—	-0.56	—	-0.65	—	ns
t <sub>HADDR_PFU</sub>	Address Hold Time	0.71	—	0.85	—	0.99	—	ns
t <sub>SUWREN_PFU</sub>	Write/Read Enable Setup Time	-0.22	—	-0.26	—	-0.30	—	ns
t <sub>HWREN_PFU</sub>	Write/Read Enable Hold Time	0.33	—	0.40	—	0.47	—	ns
<b>PIO Input/Output Buffer Timing</b>								
t <sub>IN_PIO</sub>	Input Buffer Delay	—	0.75	—	0.90	—	1.06	ns
t <sub>OUT_PIO</sub>	Output Buffer Delay	—	1.29	—	1.54	—	1.80	ns
<b>EBR Timing (1200 and 2280 Devices Only)</b>								
t <sub>CO_EBR</sub>	Clock to output from Address or Data with no output register	—	2.24	—	2.69	—	3.14	ns
t <sub>COO_EBR</sub>	Clock to output from EBR output Register	—	0.54	—	0.64	—	0.75	ns
t <sub>SUDATA_EBR</sub>	Setup Data to EBR Memory	-0.26	—	-0.31	—	-0.37	—	ns
t <sub>HDATA_EBR</sub>	Hold Data to EBR Memory	0.41	—	0.49	—	0.57	—	ns
t <sub>SUADDR_EBR</sub>	Setup Address to EBR Memory	-0.26	—	-0.31	—	-0.37	—	ns
t <sub>HADDR_EBR</sub>	Hold Address to EBR Memory	0.41	—	0.49	—	0.57	—	ns
t <sub>SUWREN_EBR</sub>	Setup Write/Read Enable to EBR Memory	-0.17	—	-0.20	—	-0.23	—	ns
t <sub>HWREN_EBR</sub>	Hold Write/Read Enable to EBR Memory	0.26	—	0.31	—	0.36	—	ns
t <sub>SUCE_EBR</sub>	Clock Enable Setup Time to EBR Output Register	0.19	—	0.23	—	0.27	—	ns
t <sub>HCE_EBR</sub>	Clock Enable Hold Time to EBR Output Register	-0.13	—	-0.16	—	-0.18	—	ns
t <sub>RSTO_EBR</sub>	Reset To Output Delay Time from EBR Output Register	—	1.03	—	1.23	—	1.44	ns
<b>PLL Parameters (1200 and 2280 Devices Only)</b>								
t <sub>RSTREC</sub>	Reset Recovery to Rising Clock	1.00	—	1.00	—	1.00	—	ns
t <sub>RSTSU</sub>	Reset Signal Setup Time	1.00	—	1.00	—	1.00	—	ns

1. Internal parameters are characterized but not tested on every device.

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### Signal Descriptions

Signal Name	I/O	Descriptions
<b>General Purpose</b>		
P[Edge] [Row/Column Number]_[A/B/C/D/E/F]	I/O	<p>[Edge] indicates the edge of the device on which the pad is located. Valid edge designations are L (Left), B (Bottom), R (Right), T (Top).</p> <p>[Row/Column Number] indicates the PFU row or the column of the device on which the PIO Group exists. When Edge is T (Top) or (Bottom), only need to specify Row Number. When Edge is L (Left) or R (Right), only need to specify Column Number.</p> <p>[A/B/C/D/E/F] indicates the PIO within the group to which the pad is connected.</p> <p>Some of these user programmable pins are shared with special function pins. When not used as special function pins, these pins can be programmed as I/Os for user logic.</p> <p>During configuration of the user-programmable I/Os, the user has an option to tri-state the I/Os and enable an internal pull-up resistor. This option also applies to unused pins (or those not bonded to a package pin). The default during configuration is for user-programmable I/Os to be tri-stated with an internal pull-up resistor enabled. When the device is erased, I/Os will be tri-stated with an internal pull-up resistor enabled.</p>
GSRN	I	Global RESET signal (active low). Dedicated pad, when not in use it can be used as an I/O pin.
TSALL	I	TSALL is a dedicated pad for the global output enable signal. When TSALL is high all the outputs are tristated. It is a dual function pin. When not in use, it can be used as an I/O pin.
NC	—	No connect.
GND	—	GND - Ground. Dedicated pins.
V <sub>CC</sub>	—	VCC - The power supply pins for core logic. Dedicated pins.
V <sub>CCAUX</sub>	—	VCCAUX - the Auxiliary power supply pin. This pin powers up a variety of internal circuits including all the differential and referenced input buffers. Dedicated pins.
V <sub>CCIOx</sub>	—	V <sub>CCIO</sub> - The power supply pins for I/O Bank x. Dedicated pins.
SLEEPN <sup>1</sup>	I	Sleep Mode pin - Active low sleep pin. <sup>b</sup> When this pin is held high, the device operates normally. <sup>b</sup> This pin has a weak internal pull-up, but when unused, an external pull-up to V <sub>CC</sub> is recommended. When driven low, the device moves into Sleep mode after a specified time.
<b>PLL and Clock Functions</b> (Used as user programmable I/O pins when not used for PLL or clock pins)		
[LOC][0]_PLL[T, C]_IN	—	Reference clock (PLL) input Pads: [LOC] indicates location. Valid designations are ULM (Upper PLL) and LLM (Lower PLL). T = true and C = complement.
[LOC][0]_PLL[T, C]_FB	—	Optional feedback (PLL) input Pads: [LOC] indicates location. Valid designations are ULM (Upper PLL) and LLM (Lower PLL). T = true and C = complement.
PCLK [n]_[1:0]	—	Primary Clock Pads, n per side.
<b>Test and Programming</b> (Dedicated pins)		
TMS	I	Test Mode Select input pin, used to control the 1149.1 state machine.
TCK	I	Test Clock input pin, used to clock the 1149.1 state machine.
TDI	I	Test Data input pin, used to load data into the device using an 1149.1 state machine.
TDO	O	Output pin -Test Data output pin used to shift data out of the device using 1149.1.

<sup>1</sup>. Applies to MachXO "C" devices only. NC for "E" devices.

## Power Supply and NC (Cont.)

Signal	132 csBGA <sup>1</sup>	256 caBGA / 256 ftBGA <sup>1</sup>	324 ftBGA <sup>1</sup>
VCC	H3, P6, G12, C7	G7, G10, K7, K10	F14, G11, G9, H7, L7, M9
VCCIO0	<b>LCMxo640:</b> B11, C5 <b>LCMxo1200/2280:</b> C5	<b>LCMxo640:</b> F8, F7, F9, F10 <b>LCMxo1200/2280:</b> F8, F7	G8, G7
VCCIO1	<b>LCMxo640:</b> L12, E12 <b>LCMxo1200/2280:</b> B11	<b>LCMxo640:</b> H11, G11, K11, J11 <b>LCMxo1200/2280:</b> F9, F10	G12, G10
VCCIO2	<b>LCMxo640:</b> N2, M10 <b>LCMxo1200/2280:</b> E12	<b>LCMxo640:</b> L9, L10, L8, L7 <b>LCMxo1200/2280:</b> H11, G11	J12, H12
VCCIO3	<b>LCMxo640:</b> D2, K3 <b>LCMxo1200/2280:</b> L12	<b>LCMxo640:</b> K6, J6, H6, G6 <b>LCMxo1200/2280:</b> K11, J11	L12, K12
VCCIO4	<b>LCMxo640:</b> None <b>LCMxo1200/2280:</b> M10	<b>LCMxo640:</b> None <b>LCMxo1200/2280:</b> L9, L10	M12, M11
VCCIO5	<b>LCMxo640:</b> None <b>LCMxo1200/2280:</b> N2	<b>LCMxo640:</b> None <b>LCMxo1200/2280:</b> L8, L7	M8, R9
VCCIO6	<b>LCMxo640:</b> None <b>LCMxo1200/2280:</b> K3	<b>LCMxo640:</b> None <b>LCMxo1200/2280:</b> K6, J6	M7, K7
VCCIO7	<b>LCMxo640:</b> None <b>LCMxo1200/2280:</b> D2	<b>LCMxo640:</b> None <b>LCMxo1200/2280:</b> H6, G6	H6, J7
VCCAUX	P7, A7	T9, A8	M10, F9
GND <sup>2</sup>	F1, P9, J14, C9, A10, B4, L13, D13, P2, N11, E1, L2	A1, A16, F11, G8, G9, H7, H8, H9, H10, J7, J8, J9, J10, K8, K9, L6, T1, T16	E14, F16, H10, H11, H8, H9, J10, J11, J4, J8, J9, K10, K11, K17, K8, K9, L10, L11, L8, L9, N2, P14, P5, R7
NC <sup>3</sup>	—	<b>LCMxo640:</b> E4, E5, F5, F6, C3, C2, G4, G5, H4, H5, K5, K4, M5, M4, P2, P3, N5, N6, M7, M8, N10, N11, R15, R16, P15, P16, M11, L11, N12, N13, M13, M12, K12, J12, F12, F13, E12, E13, D13, D14, B15, A15, C14, B14, E11, E10, E7, E6, D4, D3, B3, B2 <b>LCMxo1200:</b> None <b>LCMxo2280:</b> None	—

1. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.
2. All grounds must be electrically connected at the board level. For fpBGA and ftBGA packages, the total number of GND balls is less than the actual number of GND logic connections from the die to the common package GND plane.
3. NC pins should not be connected to any active signals, VCC or GND.

**LCMxo256 and LCMxo640 Logic Signal Connections: 100 csBGA (Cont.)**

LCMxo256					LCMxo640				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
A4	GNDIO0	0			A4	GNDIO0	0		
B4	PT3A	0		T	B4	PT3B	0		C
A3	PT2F	0		C	A3	PT3A	0		T
B3	PT2E	0		T	B3	PT2F	0		C
A2	PT2D	0		C	A2	PT2E	0		T
C3	PT2C	0		T	C3	PT2B	0		C
A1	PT2B	0		C	A1	PT2C	0		
B2	PT2A	0		T	B2	PT2A	0		T
N9	GND	-			N9	GND	-		
B9	GND	-			B9	GND	-		
B5	VCCIO0	0			B5	VCCIO0	0		
A14	VCCIO0	0			A14	VCCIO1	1		
H14	VCCIO0	0			H14	VCCIO1	1		
P10	VCCIO1	1			P10	VCCIO2	2		
G1	VCCIO1	1			G1	VCCIO3	3		
P1	VCCIO1	1			P1	VCCIO3	3		

\*NC for "E" devices.

\*\*Primary clock inputs are single-ended.

**LCMxo640, LCMxo1200 and LCMxo2280 Logic Signal Connections:  
 256 caBGA / 256 ftBGA**

LCMxo640					LCMxo1200					LCMxo2280				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
GND	GNDIO3	3			GND	GNDIO7	7			GND	GNDIO7	7		
VCCIO3	VCCIO3	3			VCCIO7	VCCIO7	7			VCCIO7	VCCIO7	7		
E4	NC				E4	PL2A	7		T	E4	PL2A	7	LUM0_PLLT_FB_A	T
E5	NC				E5	PL2B	7		C	E5	PL2B	7	LUM0_PLLC_FB_A	C
F5	NC				F5	PL3A	7		T*	F5	PL3A	7		T*
F6	NC				F6	PL3B	7		C*	F6	PL3B	7		C*
F3	PL3A	3		T	F3	PL3C	7		T	F3	PL3C	7	LUM0_PLLT_IN_A	T
F4	PL3B	3		C	F4	PL3D	7		C	F4	PL3D	7	LUM0_PLLC_IN_A	C
E3	PL2C	3		T	E3	PL4A	7		T*	E3	PL4A	7		T*
E2	PL2D	3		C	E2	PL4B	7		C*	E2	PL4B	7		C*
C3	NC				C3	PL4C	7		T	C3	PL4C	7		T
C2	NC				C2	PL4D	7		C	C2	PL4D	7		C
B1	PL2A	3		T	B1	PL5A	7		T*	B1	PL5A	7		T*
C1	PL2B	3		C	C1	PL5B	7		C*	C1	PL5B	7		C*
VCCIO3	VCCIO3	3			VCCIO7	VCCIO7	7			VCCIO7	VCCIO7	7		
GND	GNDIO3	3			GND	GNDIO7	7			GND	GNDIO7	7		
D2	PL3C	3		T	D2	PL5C	7		T	D2	PL6C	7		T
D1	PL3D	3		C	D1	PL5D	7		C	D1	PL6D	7		C
F2	PL5A	3		T	F2	PL6A	7		T*	F2	PL7A	7		T*
G2	PL5B	3	GSRN	C	G2	PL6B	7	GSRN	C*	G2	PL7B	7	GSRN	C*
E1	PL4A	3		T	E1	PL6C	7		T	E1	PL7C	7		T
F1	PL4B	3		C	F1	PL6D	7		C	F1	PL7D	7		C
G4	NC				G4	PL7A	7		T*	G4	PL8A	7		T*
G5	NC				G5	PL7B	7		C*	G5	PL8B	7		C*
GND	GND	-			GND	GND	-			GND	GND	-		
G3	PL4C	3		T	G3	PL7C	7		T	G3	PL8C	7		T
H3	PL4D	3		C	H3	PL7D	7		C	H3	PL8D	7		C
H4	NC				H4	PL8A	7		T*	H4	PL9A	7		T*
H5	NC				H5	PL8B	7		C*	H5	PL9B	7		C*
-	-				VCCIO7	VCCIO7	7			VCCIO7	VCCIO7	7		
-	-				GND	GNDIO7	7			GND	GNDIO7	7		
G1	PL5C	3		T	G1	PL8C	7		T	G1	PL10C	7		T
H1	PL5D	3		C	H1	PL8D	7		C	H1	PL10D	7		C
H2	PL6A	3		T	H2	PL9A	6		T*	H2	PL11A	6		T*
J2	PL6B	3		C	J2	PL9B	6		C*	J2	PL11B	6		C*
J3	PL7C	3		T	J3	PL9C	6		T	J3	PL11C	6		T
K3	PL7D	3		C	K3	PL9D	6		C	K3	PL11D	6		C
J1	PL6C	3		T	J1	PL10A	6		T*	J1	PL12A	6		T*
-	-				VCCIO6	VCCIO6	6			VCCIO6	VCCIO6	6		
-	-				GND	GNDIO6	6			GND	GNDIO6	6		
K1	PL6D	3		C	K1	PL10B	6		C*	K1	PL12B	6		C*
K2	PL9A	3		T	K2	PL10C	6		T	K2	PL12C	6		T
L2	PL9B	3		C	L2	PL10D	6		C	L2	PL12D	6		C
L1	PL7A	3		T	L1	PL11A	6		T*	L1	PL13A	6		T*
M1	PL7B	3		C	M1	PL11B	6		C*	M1	PL13B	6		C*
P1	PL8D	3		C	P1	PL11D	6		C	P1	PL14D	6		C
N1	PL8C	3	TSALL	T	N1	PL11C	6	TSALL	T	N1	PL14C	6	TSALL	T
L3	PL10A	3		T	L3	PL12A	6		T*	L3	PL15A	6		T*
M3	PL10B	3		C	M3	PL12B	6		C*	M3	PL15B	6		C*
M2	PL9C	3		T	M2	PL12C	6		T	M2	PL15C	6		T
N2	PL9D	3		C	N2	PL12D	6		C	N2	PL15D	6		C
VCCIO3	VCCIO3	3			VCCIO6	VCCIO6	6			VCCIO6	VCCIO6	6		
GND	GNDIO3	3			GND	GNDIO6	6			GND	GNDIO6	6		

**LCMxo2280 Logic Signal Connections: 324 ftBGA (Cont.)**

LCMxo2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
T2	PL20B	6		C
P6	TMS	5	TMS	
V1	PB2A	5		T
U2	PB2B	5		C
T3	PB2C	5		T
N7	TCK	5	TCK	
R4	PB2D	5		C
R5	PB3A	5		T
T4	PB3B	5		C
VCC	VCC	-		
R6	PB3C	5		T
P7	PB3D	5		C
U3	PB4A	5		T
T5	PB4B	5		C
V2	PB4C	5		T
N8	TDO	5	TDO	
V3	PB4D	5		C
T6	PB5A	5		T
GND	GNDIO5	5		
VCCIO5	VCCIO5	5		
U4	PB5B	5		C
P8	PB5C	5		T
T7	PB5D	5		C
V4	TDI	5	TDI	
R8	PB6A	5		T
N9	PB6B	5		C
U5	PB6C	5		T
V5	PB6D	5		C
U6	PB7A	5		T
VCC	VCC	-		
V6	PB7B	5		C
P9	PB7C	5		T
T8	PB7D	5		C
U7	PB8A	5		T
V7	PB8B	5		C
M10	VCCAUX	-		
U8	PB8C	5		T
V8	PB8D	5		C
VCCIO5	VCCIO5	5		
GND	GNDIO5	5		
T9	PB8E	5		T
U9	PB8F	5		C
V9	PB9A	4		T

**LCMxo2280 Logic Signal Connections: 324 ftBGA (Cont.)**

LCMxo2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
GND	GNDIO3	3		
VCCIO3	VCCIO3	3		
P15	PR20B	3		C
N14	PR20A	3		T
N15	PR19B	3		C
M13	PR19A	3		T
R15	PR18B	3		C*
T16	PR18A	3		T*
N16	PR17D	3		C
M14	PR17C	3		T
U17	PR17B	3		C*
VCC	VCC	-		
U18	PR17A	3		T*
R17	PR16D	3		C
R16	PR16C	3		T
P16	PR16B	3		C*
VCCIO3	VCCIO3	3		
GND	GNDIO3	3		
P17	PR16A	3		T*
L13	PR15D	3		C
M15	PR15C	3		T
T17	PR15B	3		C*
T18	PR15A	3		T*
L14	PR14D	3		C
L15	PR14C	3		T
R18	PR14B	3		C*
P18	PR14A	3		T*
GND	GND	-		
K15	PR13D	3		C
K13	PR13C	3		T
N17	PR13B	3		C*
N18	PR13A	3		T*
K16	PR12D	3		C
K14	PR12C	3		T
M16	PR12B	3		C*
L16	PR12A	3		T*
GND	GNDIO3	3		
VCCIO3	VCCIO3	3		
J16	PR11D	3		C
J14	PR11C	3		T
M17	PR11B	3		C*
L17	PR11A	3		T*
J15	PR10D	2		C

**LCMxo2280 Logic Signal Connections: 324 ftBGA (Cont.)**

LCMxo2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
G8	VCCIO0	0		
G7	VCCIO0	0		

\* Supports true LVDS outputs.

\*\* NC for "E" devices.

\*\*\* Primary clock inputs are single-ended.

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo1200E-3T100C	1200	1.2V	73	-3	TQFP	100	COM
LCMxo1200E-4T100C	1200	1.2V	73	-4	TQFP	100	COM
LCMxo1200E-5T100C	1200	1.2V	73	-5	TQFP	100	COM
LCMxo1200E-3T144C	1200	1.2V	113	-3	TQFP	144	COM
LCMxo1200E-4T144C	1200	1.2V	113	-4	TQFP	144	COM
LCMxo1200E-5T144C	1200	1.2V	113	-5	TQFP	144	COM
LCMxo1200E-3M132C	1200	1.2V	101	-3	csBGA	132	COM
LCMxo1200E-4M132C	1200	1.2V	101	-4	csBGA	132	COM
LCMxo1200E-5M132C	1200	1.2V	101	-5	csBGA	132	COM
LCMxo1200E-3B256C	1200	1.2V	211	-3	caBGA	256	COM
LCMxo1200E-4B256C	1200	1.2V	211	-4	caBGA	256	COM
LCMxo1200E-5B256C	1200	1.2V	211	-5	caBGA	256	COM
LCMxo1200E-3FT256C	1200	1.2V	211	-3	ftBGA	256	COM
LCMxo1200E-4FT256C	1200	1.2V	211	-4	ftBGA	256	COM
LCMxo1200E-5FT256C	1200	1.2V	211	-5	ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo2280E-3T100C	2280	1.2V	73	-3	TQFP	100	COM
LCMxo2280E-4T100C	2280	1.2V	73	-4	TQFP	100	COM
LCMxo2280E-5T100C	2280	1.2V	73	-5	TQFP	100	COM
LCMxo2280E-3T144C	2280	1.2V	113	-3	TQFP	144	COM
LCMxo2280E-4T144C	2280	1.2V	113	-4	TQFP	144	COM
LCMxo2280E-5T144C	2280	1.2V	113	-5	TQFP	144	COM
LCMxo2280E-3M132C	2280	1.2V	101	-3	csBGA	132	COM
LCMxo2280E-4M132C	2280	1.2V	101	-4	csBGA	132	COM
LCMxo2280E-5M132C	2280	1.2V	101	-5	csBGA	132	COM
LCMxo2280E-3B256C	2280	1.2V	211	-3	caBGA	256	COM
LCMxo2280E-4B256C	2280	1.2V	211	-4	caBGA	256	COM
LCMxo2280E-5B256C	2280	1.2V	211	-5	caBGA	256	COM
LCMxo2280E-3FT256C	2280	1.2V	211	-3	ftBGA	256	COM
LCMxo2280E-4FT256C	2280	1.2V	211	-4	ftBGA	256	COM
LCMxo2280E-5FT256C	2280	1.2V	211	-5	ftBGA	256	COM
LCMxo2280E-3FT324C	2280	1.2V	271	-3	ftBGA	324	COM
LCMxo2280E-4FT324C	2280	1.2V	271	-4	ftBGA	324	COM
LCMxo2280E-5FT324C	2280	1.2V	271	-5	ftBGA	324	COM

## Conventional Packaging

### Industrial

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo256C-3T100I	256	1.8V/2.5V/3.3V	78	-3	TQFP	100	IND
LCMxo256C-4T100I	256	1.8V/2.5V/3.3V	78	-4	TQFP	100	IND
LCMxo256C-3M100I	256	1.8V/2.5V/3.3V	78	-3	csBGA	100	IND
LCMxo256C-4M100I	256	1.8V/2.5V/3.3V	78	-4	csBGA	100	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo640C-3T100I	640	1.8V/2.5V/3.3V	74	-3	TQFP	100	IND
LCMxo640C-4T100I	640	1.8V/2.5V/3.3V	74	-4	TQFP	100	IND
LCMxo640C-3M100I	640	1.8V/2.5V/3.3V	74	-3	csBGA	100	IND
LCMxo640C-4M100I	640	1.8V/2.5V/3.3V	74	-4	csBGA	100	IND
LCMxo640C-3T144I	640	1.8V/2.5V/3.3V	113	-3	TQFP	144	IND
LCMxo640C-4T144I	640	1.8V/2.5V/3.3V	113	-4	TQFP	144	IND
LCMxo640C-3M132I	640	1.8V/2.5V/3.3V	101	-3	csBGA	132	IND
LCMxo640C-4M132I	640	1.8V/2.5V/3.3V	101	-4	csBGA	132	IND
LCMxo640C-3B256I	640	1.8V/2.5V/3.3V	159	-3	caBGA	256	IND
LCMxo640C-4B256I	640	1.8V/2.5V/3.3V	159	-4	caBGA	256	IND
LCMxo640C-3FT256I	640	1.8V/2.5V/3.3V	159	-3	ftBGA	256	IND
LCMxo640C-4FT256I	640	1.8V/2.5V/3.3V	159	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo1200C-3T100I	1200	1.8V/2.5V/3.3V	73	-3	TQFP	100	IND
LCMxo1200C-4T100I	1200	1.8V/2.5V/3.3V	73	-4	TQFP	100	IND
LCMxo1200C-3T144I	1200	1.8V/2.5V/3.3V	113	-3	TQFP	144	IND
LCMxo1200C-4T144I	1200	1.8V/2.5V/3.3V	113	-4	TQFP	144	IND
LCMxo1200C-3M132I	1200	1.8V/2.5V/3.3V	101	-3	csBGA	132	IND
LCMxo1200C-4M132I	1200	1.8V/2.5V/3.3V	101	-4	csBGA	132	IND
LCMxo1200C-3B256I	1200	1.8V/2.5V/3.3V	211	-3	caBGA	256	IND
LCMxo1200C-4B256I	1200	1.8V/2.5V/3.3V	211	-4	caBGA	256	IND
LCMxo1200C-3FT256I	1200	1.8V/2.5V/3.3V	211	-3	ftBGA	256	IND
LCMxo1200C-4FT256I	1200	1.8V/2.5V/3.3V	211	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo2280C-3T100I	2280	1.8V/2.5V/3.3V	73	-3	TQFP	100	IND
LCMxo2280C-4T100I	2280	1.8V/2.5V/3.3V	73	-4	TQFP	100	IND
LCMxo2280C-3T144I	2280	1.8V/2.5V/3.3V	113	-3	TQFP	144	IND
LCMxo2280C-4T144I	2280	1.8V/2.5V/3.3V	113	-4	TQFP	144	IND
LCMxo2280C-3M132I	2280	1.8V/2.5V/3.3V	101	-3	csBGA	132	IND
LCMxo2280C-4M132I	2280	1.8V/2.5V/3.3V	101	-4	csBGA	132	IND
LCMxo2280C-3B256I	2280	1.8V/2.5V/3.3V	211	-3	caBGA	256	IND
LCMxo2280C-4B256I	2280	1.8V/2.5V/3.3V	211	-4	caBGA	256	IND
LCMxo2280C-3FT256I	2280	1.8V/2.5V/3.3V	211	-3	ftBGA	256	IND
LCMxo2280C-4FT256I	2280	1.8V/2.5V/3.3V	211	-4	ftBGA	256	IND
LCMxo2280C-3FT324I	2280	1.8V/2.5V/3.3V	271	-3	ftBGA	324	IND
LCMxo2280C-4FT324I	2280	1.8V/2.5V/3.3V	271	-4	ftBGA	324	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo1200E-3TN100C	1200	1.2V	73	-3	Lead-Free TQFP	100	COM
LCMxo1200E-4TN100C	1200	1.2V	73	-4	Lead-Free TQFP	100	COM
LCMxo1200E-5TN100C	1200	1.2V	73	-5	Lead-Free TQFP	100	COM
LCMxo1200E-3TN144C	1200	1.2V	113	-3	Lead-Free TQFP	144	COM
LCMxo1200E-4TN144C	1200	1.2V	113	-4	Lead-Free TQFP	144	COM
LCMxo1200E-5TN144C	1200	1.2V	113	-5	Lead-Free TQFP	144	COM
LCMxo1200E-3MN132C	1200	1.2V	101	-3	Lead-Free csBGA	132	COM
LCMxo1200E-4MN132C	1200	1.2V	101	-4	Lead-Free csBGA	132	COM
LCMxo1200E-5MN132C	1200	1.2V	101	-5	Lead-Free csBGA	132	COM
LCMxo1200E-3BN256C	1200	1.2V	211	-3	Lead-Free caBGA	256	COM
LCMxo1200E-4BN256C	1200	1.2V	211	-4	Lead-Free caBGA	256	COM
LCMxo1200E-5BN256C	1200	1.2V	211	-5	Lead-Free caBGA	256	COM
LCMxo1200E-3FTN256C	1200	1.2V	211	-3	Lead-Free ftBGA	256	COM
LCMxo1200E-4FTN256C	1200	1.2V	211	-4	Lead-Free ftBGA	256	COM
LCMxo1200E-5FTN256C	1200	1.2V	211	-5	Lead-Free ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo2280E-3TN100C	2280	1.2V	73	-3	Lead-Free TQFP	100	COM
LCMxo2280E-4TN100C	2280	1.2V	73	-4	Lead-Free TQFP	100	COM
LCMxo2280E-5TN100C	2280	1.2V	73	-5	Lead-Free TQFP	100	COM
LCMxo2280E-3TN144C	2280	1.2V	113	-3	Lead-Free TQFP	144	COM
LCMxo2280E-4TN144C	2280	1.2V	113	-4	Lead-Free TQFP	144	COM
LCMxo2280E-5TN144C	2280	1.2V	113	-5	Lead-Free TQFP	144	COM
LCMxo2280E-3MN132C	2280	1.2V	101	-3	Lead-Free csBGA	132	COM
LCMxo2280E-4MN132C	2280	1.2V	101	-4	Lead-Free csBGA	132	COM
LCMxo2280E-5MN132C	2280	1.2V	101	-5	Lead-Free csBGA	132	COM
LCMxo2280E-3BN256C	2280	1.2V	211	-3	Lead-Free caBGA	256	COM
LCMxo2280E-4BN256C	2280	1.2V	211	-4	Lead-Free caBGA	256	COM
LCMxo2280E-5BN256C	2280	1.2V	211	-5	Lead-Free caBGA	256	COM
LCMxo2280E-3FTN256C	2280	1.2V	211	-3	Lead-Free ftBGA	256	COM
LCMxo2280E-4FTN256C	2280	1.2V	211	-4	Lead-Free ftBGA	256	COM
LCMxo2280E-5FTN256C	2280	1.2V	211	-5	Lead-Free ftBGA	256	COM
LCMxo2280E-3FTN324C	2280	1.2V	271	-3	Lead-Free ftBGA	324	COM
LCMxo2280E-4FTN324C	2280	1.2V	271	-4	Lead-Free ftBGA	324	COM
LCMxo2280E-5FTN324C	2280	1.2V	271	-5	Lead-Free ftBGA	324	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo256E-3TN100I	256	1.2V	78	-3	Lead-Free TQFP	100	IND
LCMxo256E-4TN100I	256	1.2V	78	-4	Lead-Free TQFP	100	IND
LCMxo256E-3MN100I	256	1.2V	78	-3	Lead-Free csBGA	100	IND
LCMxo256E-4MN100I	256	1.2V	78	-4	Lead-Free csBGA	100	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo640E-3TN100I	640	1.2V	74	-3	Lead-Free TQFP	100	IND
LCMxo640E-4TN100I	640	1.2V	74	-4	Lead-Free TQFP	100	IND
LCMxo640E-3MN100I	640	1.2V	74	-3	Lead-Free csBGA	100	IND
LCMxo640E-4MN100I	640	1.2V	74	-4	Lead-Free csBGA	100	IND
LCMxo640E-3TN144I	640	1.2V	113	-3	Lead-Free TQFP	144	IND
LCMxo640E-4TN144I	640	1.2V	113	-4	Lead-Free TQFP	144	IND
LCMxo640E-3MN132I	640	1.2V	101	-3	Lead-Free csBGA	132	IND
LCMxo640E-4MN132I	640	1.2V	101	-4	Lead-Free csBGA	132	IND
LCMxo640E-3BN256I	640	1.2V	159	-3	Lead-Free caBGA	256	IND
LCMxo640E-4BN256I	640	1.2V	159	-4	Lead-Free caBGA	256	IND
LCMxo640E-3FTN256I	640	1.2V	159	-3	Lead-Free ftBGA	256	IND
LCMxo640E-4FTN256I	640	1.2V	159	-4	Lead-Free ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo1200E-3TN100I	1200	1.2V	73	-3	Lead-Free TQFP	100	IND
LCMxo1200E-4TN100I	1200	1.2V	73	-4	Lead-Free TQFP	100	IND
LCMxo1200E-3TN144I	1200	1.2V	113	-3	Lead-Free TQFP	144	IND
LCMxo1200E-4TN144I	1200	1.2V	113	-4	Lead-Free TQFP	144	IND
LCMxo1200E-3MN132I	1200	1.2V	101	-3	Lead-Free csBGA	132	IND
LCMxo1200E-4MN132I	1200	1.2V	101	-4	Lead-Free csBGA	132	IND
LCMxo1200E-3BN256I	1200	1.2V	211	-3	Lead-Free caBGA	256	IND
LCMxo1200E-4BN256I	1200	1.2V	211	-4	Lead-Free caBGA	256	IND
LCMxo1200E-3FTN256I	1200	1.2V	211	-3	Lead-Free ftBGA	256	IND
LCMxo1200E-4FTN256I	1200	1.2V	211	-4	Lead-Free ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo2280E-3TN100I	2280	1.2V	73	-3	Lead-Free TQFP	100	IND
LCMxo2280E-4TN100I	2280	1.2V	73	-4	Lead-Free TQFP	100	IND
LCMxo2280E-3TN144I	2280	1.2V	113	-3	Lead-Free TQFP	144	IND
LCMxo2280E-4TN144I	2280	1.2V	113	-4	Lead-Free TQFP	144	IND
LCMxo2280E-3MN132I	2280	1.2V	101	-3	Lead-Free csBGA	132	IND
LCMxo2280E-4MN132I	2280	1.2V	101	-4	Lead-Free csBGA	132	IND
LCMxo2280E-3BN256I	2280	1.2V	211	-3	Lead-Free caBGA	256	IND
LCMxo2280E-4BN256I	2280	1.2V	211	-4	Lead-Free caBGA	256	IND
LCMxo2280E-3FTN256I	2280	1.2V	211	-3	Lead-Free ftBGA	256	IND
LCMxo2280E-4FTN256I	2280	1.2V	211	-4	Lead-Free ftBGA	256	IND
LCMxo2280E-3FTN324I	2280	1.2V	271	-3	Lead-Free ftBGA	324	IND
LCMxo2280E-4FTN324I	2280	1.2V	271	-4	Lead-Free ftBGA	324	IND